



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

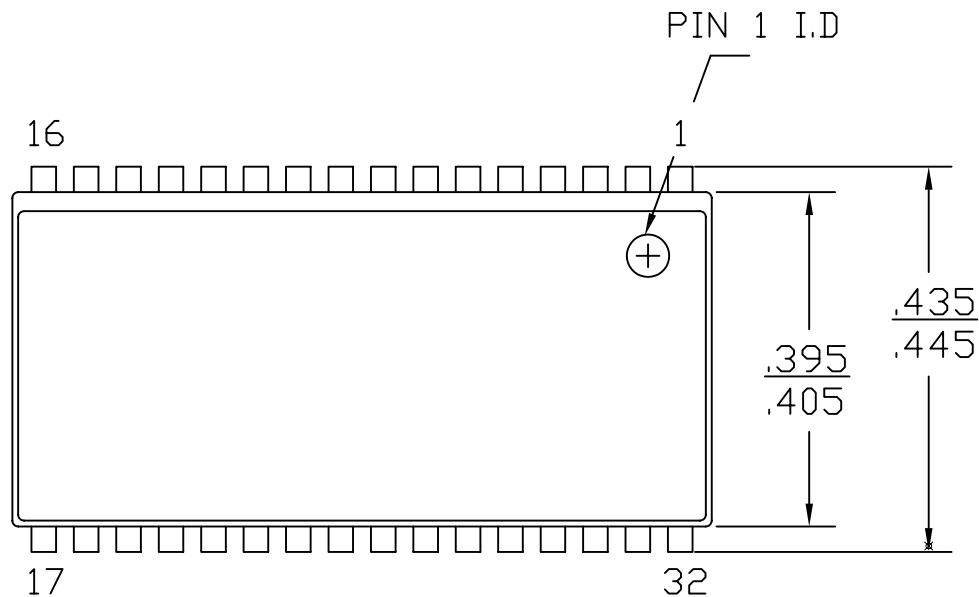
**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

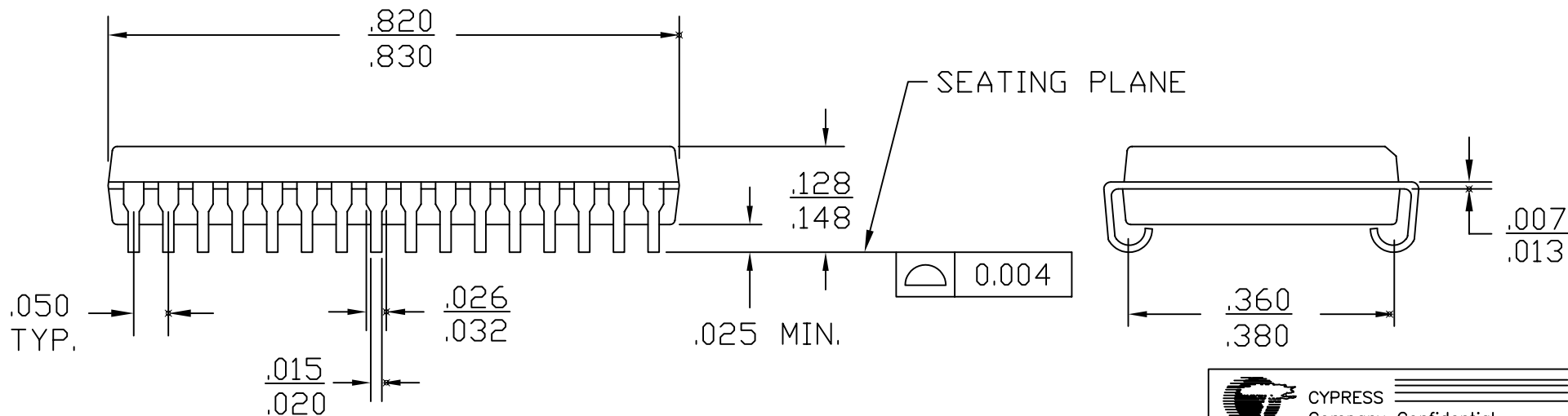
**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

# 32 Lead (400 MIL) Molded SOJ V33



DIMENSIONS IN INCHES MIN.  
MAX.



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PACKAGE CODE(S)

V32.4



CYPRESS  
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TITLE  
PACKAGE OUTLINE, 32L SOJ 400 MILS V32.4  
(MOLDED SOJ V33)

SPEC NO.  
51-85033

REV  
\*E

SCALED TO FIT

N/A

SHEET 1 OF 2

Rev.	ECN No.	Origin of Change	Description of Change
**	N/A		N/A
*A	49390		CHG. TITLE
*B	59367		REMOVE DETAIL "A"
*C	2871406		Changed template, & title from 32LD (400 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 32L SOJ 400 MILS V32.4 (MOLDED SOJ V33).
*D	3146953		ECN SUNSET NO CHANGE
*E	4257091	KTQAD/ XANC	SUNSET REVIEW. CHANGED DRAWING TEMPLATE.



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TITLE  
PACKAGE OUTLINE, 32L SOJ 400 MILS V32.4  
(MOLDED SOJ V33)

SPEC NO.  
51-85033

REV  
\*E

SCALED TO FIT      N/A      SHEET 2 OF 2

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